© Cot	erial Composition pyright 2005. IPC, Ba ational and Pan-Ame	annockburn, Illi	inois. All rights reserved u	under both	This docume level parts, t	ent is a declara he declaration	tion of the succession of the	ubstances s all lower	within the manufactur level materials for w	rer listed ite hich the ma	em. Note: if anufacturer	the item is an as has engineering	sembly with lower responsibility.
				Form Type Distribute					ials and Mfg Information				
Supplier Information													
Company name*			Company unique ID			Unique ID Authority				Response Date*			
onsemi										2025-09-07			
Contact Name			Title - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			Phone - Representative*				Email - Representative*			
Product-Env-Stewards Pr			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item N	Requester Item Number Mfr Iter		n Number Mfr Item Name			Effective Dat	e Version	N	Anufacturing Site	v	/eight*	UOM	Unit Type
	S	ZISMB5937B	T3G ZEN SMB REG	ZEN SMB REG 3W SPCL TR		2025-09-07		١	VN5		14.91	mg	Each
Manufacturing Procce	ess Information											·	
Terminal Plating / Grid Array Material Term			inal Base Alloy J-STD-020 MSL R		Rating	Peak Process Body Temperature		e Max Time at Peak	Temperatu	re Numb	er of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Allo)y	1			260 C 30			seconds 3			
Comments													
level 1 - maximum time at p	eak temperature du	ring soldering	is 10-30 seconds										
For more information regar	ding material comp	osition please 1	refer to page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et					
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted				
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).						
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.									
Supplier Digital Signature	astislav Drska	Le							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	16.81	mg	Supplier	Zinc (Zn)	7440-66-6		0.0202	mg
			Supplier	Iron (Fe)	7439-89-6		0.395	mg
			Supplier	Copper (Cu)	7440-50-8		16.3897	mg
			Supplier	Phosphorus (P)	7723-14-0		0.005	mg
Die	0.7	mg	Supplier	Silicon (Si)	7440-21-3		0.7	mg
Die Attach Solder	0.52	mg	Supplier	Silver (Ag)	7440-22-4		0.013	mg
			А	Lead (Pb)	7439-92-1	7a	0.481	mg
			Supplier	Tin (Sn)	7440-31-5		0.026	mg
Lead Frame	46.99	mg	Supplier	Zinc (Zn)	7440-66-6		0.0564	mg
			Supplier	Iron (Fe)	7439-89-6		1.1043	mg
			Supplier	Copper (Cu)	7440-50-8		45.8153	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0141	mg
Mold Compound-Black	48.07	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		4.807	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2403	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		6.9701	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		31.2455	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		4.807	mg
Plating	1.82	mg	Supplier	Tin (Sn)	7440-31-5		1.82	mg